

TH Series 2.5W/mk Thermally Conductive adhesive tapes

The TH Series of thermally conductive adhesive tapes possess extremely high 2.5W/mk Thermal Conductivity and low thermal impedance and yet maintain a high bonding strength.

The tape can be used to replace thermal filler pads, thermal grease with mechanical fixings. Applications include bonding Heat Sinks, Microprocessors, LED's, and other high power semiconductors.

Features

- Thermal Conductivity 2.5 W/m-k
- High bond strength to a variety of surfaces.
- Double sided pressure sensitive adhesive tape.
- High performance thermally conductive acrylic adhesive.

Application

- Mounting heatsinks on BGA processor or drive processor.
- Mounting heat spreader onto PCB or onto motor control PCB
- Can be used instead of heat cure adhesive, screw mounting or clip mounting.

Items	TH-10	TH-20	
Sheet Size (mm)	300 x 300		
Adhesive Type	Acrylic Adhesive		*****
Backing Type	Fiberglass		*****
Continuous Use Temp	-40~120(°C)		*****
Thickness	0.1mm	0.2mm	ASTM D374
Thickness Tolerance	0.02	0.02	ASTM D374
Voltage Breakdown	> 3000 Vac	> 4000 Vac	ASTM D149
Steel adhesion (g/25mm)	800	1000	ASTM E 1000
Thermal Impedance @50psi	0.31	0.39	
Thermal Conductivity	2.5w/m-k		ASTM D5470
Volume Resistivity (Ω-cm)	10 ¹⁴		ASTM D 257
Hardness (Shore A)	33±5		JIS K 6301A
Holding Power (25 °C /Hours)	> 48 Hours		PSTC-7
Holding Power (80 °C /Hours)	> 48 Hours		PSTC-7

Contact us for alternative thickness.

Standard roll Size: 1030mm x 30m - individual die cut shapes can be supplied
Can be provided with fiberglass reinforcement

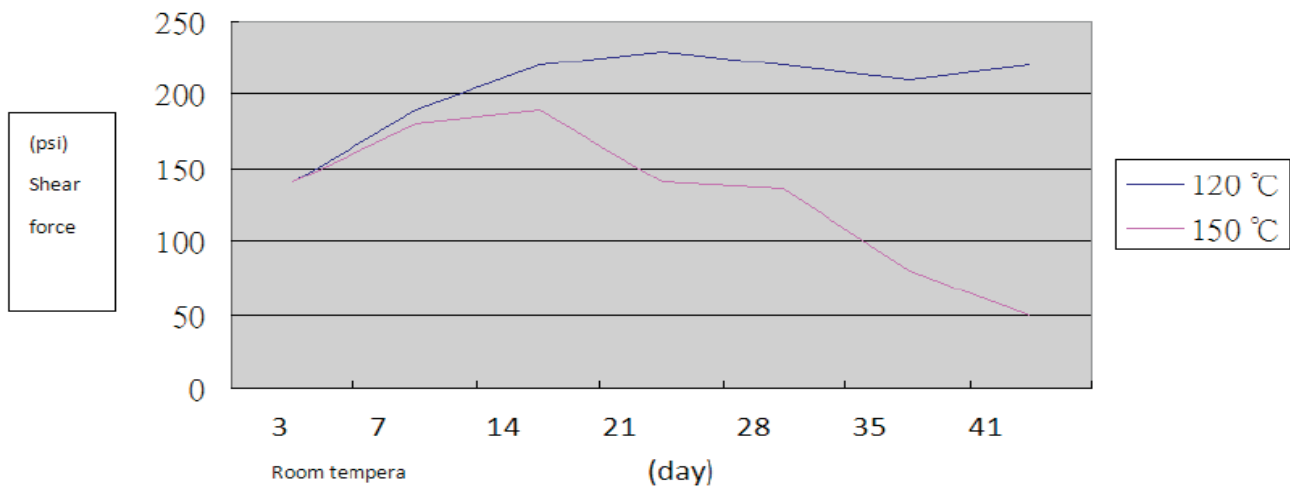
Test Data

Anti-aging properties

Long term temperature changes under shear stress test

Test conditions: bonding material for aluminium, take sample of high temperature aging test

The sample area of 1 square inch adhesive



Heating time before test

Test method: According to UL-746C test, high temperature aging conditions (100°C, a continuous 1000 hours) shear

To last at least 50% of requirements

